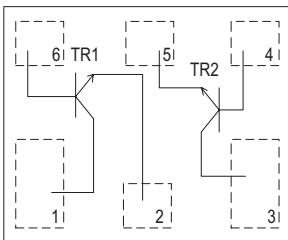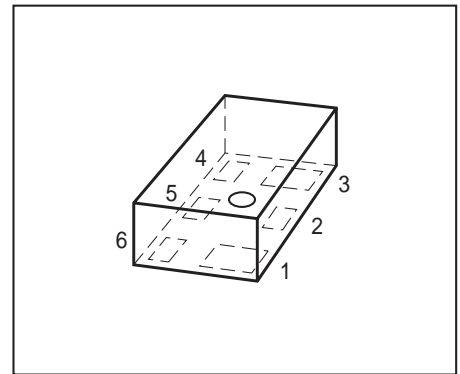**NPN Silicon RF TWIN Transistor***

- Low voltage/ low current applications

- Ideal for VCO modules and low noise amplifiers

- World's smallest SMD 6-pin leadless package

- Built in 2 transitors (TR1: die as BFR460L3,
                                    TR2: die as BFR360L3)

- Low noise figure: TR1: 1.1dB at 1.8 GHz
                              TR2: 1.0 dB at 1.8 GHz

- TR1 with excellent ESD performance
  typical value > 1500 V (HBM)

- Pb-free (RoHS compliant) package[1]

- Qualified according AEC Q101

* Short term description

ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration						Package
BFS466L6	AC	1=C1	2=E1	3=C2	4=B2	5=E2	6=B1	TSLP-6-1

[1]Pb-containing package may be available upon special request

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}		V
TR1, $T_A > 0\ °C$		4.5	
TR1, $T_A \leq 0\ °C$		4.2	
TR2, $T_A > 0\ °C$		6	
TR2, $T_A \leq 0\ °C$		6	
Collector-emitter voltage	V_{CES}		
TR1		15	
TR2		15	
Collector-base voltage	V_{CBO}		
TR1		15	
TR2		15	
Emitter-base voltage	V_{EBO}		
TR1		1.5	
TR2		2	
Collector current	I_C		mA
TR1		50	
TR2		35	

Maximum Ratings

Parameter	Symbol	Value	Unit
Base current TR1 TR2	I_B	 5 4	mA
Total power dissipation[1] TR1, $T_S \leq 104°C$ TR2, $T_S \leq 102°C$	P_{tot}	 200 210	mW
Junction temperature TR1 TR2	T_j	 150 150	°C
Ambient temperature TR1 TR2	T_A	 -65 ... 150 -65 ... 150	
Storage temperature TR1 TR2	T_{stg}	 -65 ... 150 -65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[2] TR1 TR2	R_{thJS}	 ≤ 230 ≤ 230	K/W

[1]T_S is measured on the collector lead at the soldering point to the pcb

[2]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

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Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage	$V_{(BR)CEO}$				V
TR1, I_C = 1 mA, I_B = 0		4.5	5	-	
TR2, I_C = 1 mA, I_B = 0		6	9	-	
Collector-emitter cutoff current	I_{CES}				μA
TR1, V_{CE} = 15 V, V_{BE} = 0		-	-	10	
TR2, V_{CE} = 15 V, V_{BE} = 0		-	-	10	
Collector-base cutoff current	I_{CBO}				nA
TR1, V_{CB} = 5 V, I_E = 0		-	-	100	
TR2, V_{CB} = 5 V, I_E = 0		-	-	100	
Emitter-base cutoff current	I_{EBO}				μA
TR1, V_{EB} = 0,5 V, I_C = 0		-	-	1	
TR2, V_{EB} = 1 V, I_C = 0		-	-	1	
DC current gain	h_{FE}				-
TR1, I_C = 20 mA, V_{CE} = 3 V, Pulse measured		90	120	160	
TR2, I_C = 15 mA, V_{CE} = 3 V, Pulse measured		90	120	160	

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency	f_T				GHz
TR1, I_C = 30 mA, V_{CE} = 3 V, f = 1 GHz		16	22	-	
TR2, I_C = 15 mA, V_{CE} = 3 V, f = 1 GHz		11	14	-	
Collector-base capacitance	C_{cb}				pF
TR1, V_{CB} = 3 V, f = 1 MHz, V_{BE} = 0 , emitter grounded		-	0.29	0.45	
TR2, V_{CB} = 5 V, f = 1 MHz, V_{BE} = 0 , emitter grounded		-	0.26	0.4	
Collector emitter capacitance	C_{ce}				
TR1, V_{CE} = 3 V, f = 1 MHz, V_{BE} = 0 , base grounded		-	0.14	-	
TR2, V_{CE} = 5 V, f = 1 MHz, V_{BE} = 0 , base grounded		-	0.14	-	
Emitter-base capacitance	C_{eb}				
TR1, V_{EB} = 0.5 V, f = 1 MHz, V_{CB} = 0 , collector grounded		-	0.54	-	
TR2, V_{EB} = 0.5 V, f = 1 MHz, V_{CB} = 0 , collector grounded		-	0.43	-	

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Electrical Characteristics at TA = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Noise figure	F				dB
TR1, I_C=5mA, V_{CE} = 3 V, f = 1.8 GHz, Z_S = Z_{Sopt}		-	1.1	-	
TR1, I_C=5mA, V_{CE} = 3 V, f = 3 GHz, Z_S = Z_{Sopt}		-	1.4	-	
TR2, I_C=3mA, V_{CE} = 3 V, f = 1.8 GHz, Z_S = Z_{Sopt}		-	1	-	
TR2, I_C=3mA, V_{CE} = 3 V, f = 3 GHz, Z_S = Z_{Sopt}		-	1.4	-	
Power gain, maximum available[1]	G_{ma}				
TR1, I_C = 20 mA, V_{CE} = 3 V, Z_S=Z_{Sopt}, Z_L=Z_{Lopt}, f = 1.8 GHz		-	17	-	
TR1, I_C = 20 mA, V_{CE} = 3 V, Z_S=Z_{Sopt}, Z_L=Z_{Lopt}, f = 3 GHz		-	12	-	
TR2, I_C = 15 mA, V_{CE} = 3 V, Z_S=Z_{Sopt}, Z_L=Z_{Lopt}, f = 1.8 GHz		-	16.5	-	
TR2, I_C = 15 mA, V_{CE} = 3 V, Z_S=Z_{Sopt}, Z_L=Z_{Lopt}, f = 3 GHz		-	11.5	-	
Transducer gain	$\lvert S_{21e}\rvert^2$				
TR1, I_C = 20 mA, V_{CE} = 3 V, Z_S = Z_L = 50Ω, f = 1.8GHz		-	14.5	-	
TR1, I_C = 20 mA, V_{CE} = 3 V, Z_S = Z_L = 50Ω, f = 3GHz		-	10	-	
TR2, I_C = 15 mA, V_{CE} = 3 V, Z_S = Z_L = 50Ω, f = 1.8GHz		-	13.5	-	
TR2, I_C = 15 mA, V_{CE} = 3 V, Z_S = Z_L = 50Ω, f = 3GHz		-	9.5	-	
Third order intercept point at output[2]	IP_3				dBm
TR1, V_{CE}=3V, I_C=20mA, Z_S=Z_L=50Ω, f=1.8GHz		-	28	-	
TR2, V_{CE}=3V, I_C=15mA, Z_S=Z_L=50Ω, f=1.8GHz		-	24.5	-	
1dB Compression point, at output	P_{-1dB}				
TR1, I_C=20mA, V_{CE}=3V, Z_S=Z_L=50Ω, f=1.8GHz		-	12	-	
TR1, I_C=15mA, V_{CE}=3V, Z_S=Z_L=50Ω, f=1.8GHz		-	9	-	

[1] $G_{ma} = \lvert S_{21e} / S_{12e}\rvert (k-(k^2-1)^{1/2})$

[2] IP3 value depends on termination of all intermodulation frequency components.
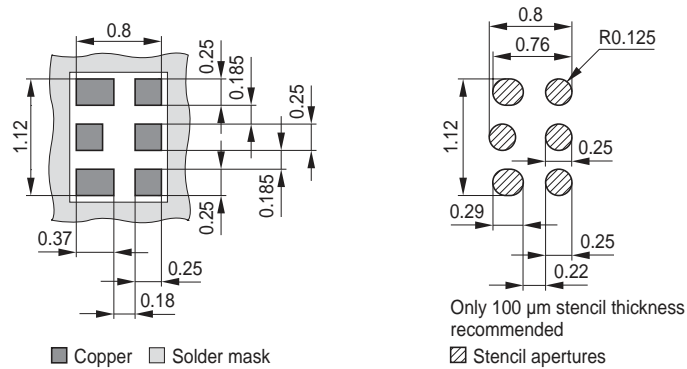Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz
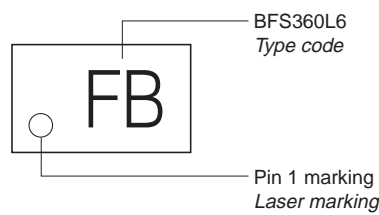
Package Outline

Top view

Bottom view

0.4⁺⁰·¹

0.05 MAX.

1) Dimension applies to plated terminal

Pin 1 marking

Foot Print

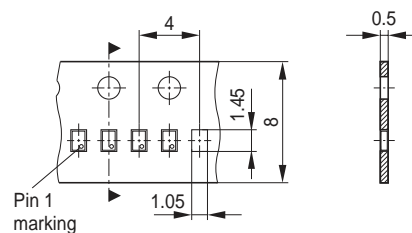For board assembly information please refer to Infineon website "Packages"

■ Copper □ Solder mask

Only 100 µm stencil thickness recommended

▨ Stencil apertures

Marking Layout (Example)

BFS360L6
Type code

FB

Pin 1 marking
Laser marking

Standard Packing

Reel ⌀180 mm = 15.000 Pieces/Reel

Pin 1
marking

Attention please!

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